

Amend claim 17 to read as follows:

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--17. A solder useful in kinetically controlled bonding of parts, the solder comprising:

a plurality of chemical element layers;

at least one of the chemical element layers defining a binary solder, the binary solder having a first melting temperature; and

another one of the chemical element layers defining a solder quenching layer;

wherein the solder formed by the chemical element layers has a usage temperature which is substantially higher than the first temperature of the binary solder.--

{ Amend claim 18 to read as follows: }

--18. The solder according to claim 17, wherein the binary solder comprises a sequence of chemical element layers each comprising a single chemical element of the binary solder, the chemical element layers forming a binary mixture close to the eutectic point of the chemical elements at the first melting temperature.--

{ Amend claim 19 to read as follows: }

--19. The solder according to claim 18, wherein the chemical element layers are gold and tin which form a binary solder mixture close to the eutectic point of gold-tin at the first melting temperature.--

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